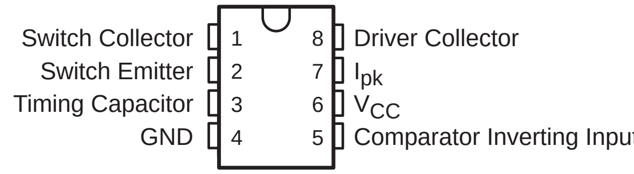
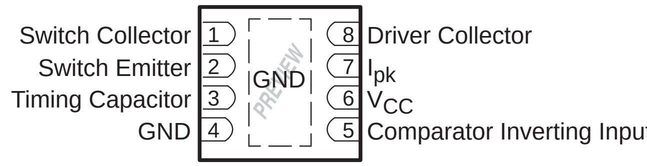
- **Qualification in Accordance With AEC-Q100†**
- **Qualified for Automotive Applications**
- **Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval**
- **Wide Input Voltage Range . . . 3 V to 40 V**
- **High Output Switch Current . . . Up to 1.5 A**
- **Adjustable Output Voltage**
- **Oscillator Frequency . . . Up to 100 kHz**
- **Precision Internal Reference . . . 2%**
- **Short-Circuit Current Limiting**
- **Low Standby Current**

† Contact factory for details. Q100 qualification data available on request.

D (SOIC) PACKAGE
(TOP VIEW)



DRJ (QFN) PACKAGE
(TOP VIEW)



description/ordering information

The MC33063A is an easy-to-use IC containing all the primary circuitry needed for building simple dc-dc converters. This device primarily consists of an internal temperature-compensated reference, a comparator, an oscillator, a PWM controller with active current limiting, a driver, and a high-current output switch; thus, the device requires minimal external components to build converters in the boost, buck, and inverting topologies.

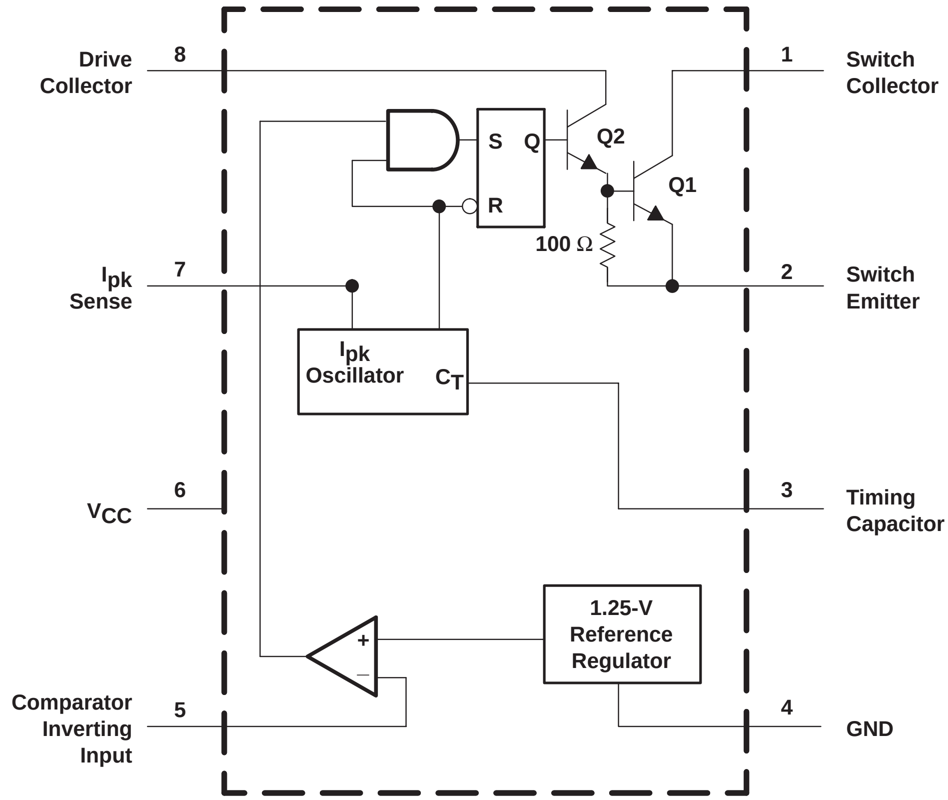
The MC33063A is characterized for operation from −40°C to 125°C.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 125°C	QFN (DRJ)	Reel of 1000	MC33063AQDRJR	PREVIEW
	SOIC (D)	Reel of 2500	MC33063AQDR	33063AQ

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

functional block diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC}	40 V
Comparator Inverting Input voltage range, V_{IR}	−0.3 V to 40 V
Switch Collector voltage, $V_{C(switch)}$	40V
Switch Emitter voltage (V_{PIN1} = 40 V), $V_{E(switch)}$	40V
Switch Collector to Switch Emitter voltage, $V_{CE(switch)}$	40V
Driver Collector voltage, $V_{C(driver)}$	40V
Driver Collector current, $I_{C(driver)}$	100 mA
Switch current, I_{SW}	1.5 A
Package thermal impedance, θ_{JA} (see Notes 1 and 2): D package	97°C/W
Operating virtual junction temperature, T_J	150°C
Storage temperature range, T_{stg}	−65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. Maximum power dissipation is a function of T_J(max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

			MIN	MAX	UNIT
V_{CC}	Supply voltage		3	40	V
T_A	Operating free-air temperature range	MC33063A	−40	125	°C

electrical characteristics, V_{CC} = 5 V, T_A = full operating range (unless otherwise noted) (see block diagram)

OSCILLATOR

PARAMETER		TEST CONDITIONS	T_A	MIN	TYP	MAX	UNIT
f_{osc}	Oscillator frequency	V_{PIN5} = 0 V, C_T = 1 nF	25°C	24	33	42	kHz
I_{chg}	Charge current	V_{CC} = 5 V to 40 V	25°C	24	35	42	µA
I_{dischg}	Discharge current	V_{CC} = 5 V to 40 V	25°C	140	220	260	µA
I_{dischg}/I_{chg}	Discharge-to-charge current ratio	V_{PIN7} = V_{CC}	25°C	5.2	6.5	7.5	
V_{Ipk}	Current-limit sense voltage	I_{dischg} = I_{chg}	25°C	250	300	350	mV

OUTPUT SWITCH (see Note 3)

PARAMETER		TEST CONDITIONS	T_A	MIN	TYP	MAX	UNIT
$V_{CE(sat)}$	Saturation voltage – Darlington connection	I_{SW} = 1 A, pins 1 and 8 connected	Full range		1	1.3	V
$V_{CE(sat)}$	Saturation voltage – non-Darlington connection (see Note 4)	I_{SW} = 1 A, R_{PIN8} = 82 Ω to V_{CC}, forced β ∼ 20	Full range		0.45	0.7	V
h_{FE}	DC current gain	I_{SW} = 1 A, V_{CE} = 5 V	25°C	50	75		
$I_{C(off)}$	Collector off-state current	V_{CE} = 40 V	Full range		0.01	100	µA

NOTES: 3. Low duty-cycle pulse testing is used to maintain junction temperature as close to ambient temperature as possible.
4. In the non-Darlington configuration, if the output switch is driven into hard saturation at low switch currents (≤300 mA) and high driver currents (≥30 mA), it may take up to 2 µs for the switch to come out of saturation. This condition effectively shortens the off time at frequencies ≥30 kHz, becoming magnified as temperature increases. The following output drive condition is recommended in the non-Darlington configuration:
Forced β of output switch = $I_{C,SW}$ / ($I_{C,driver}$ − 7 mA) ≥ 10,
where ∼ 7 mA is required by the 100-Ω resistor in the emitter of the driver to forward bias the V_{be} of the switch.

COMPARATOR

PARAMETER		TEST CONDITIONS	T_A	MIN	TYP	MAX	UNIT
V_{th}	Threshold voltage		25°C	1.225	1.25	1.275	V
			Full range	1.21		1.29	
ΔV_{th}	Threshold-voltage line regulation	V_{CC} = 5 V to 40 V	Full range		1.4	5	mV
I_{IB}	Input bias current	V_{IN} = 0 V	Full range		−20	−400	nA

TOTAL DEVICE

PARAMETER		TEST CONDITIONS	T_A	MIN	MAX	UNIT
I_{CC}	Supply current	V_{CC} = 5 V to 40 V, C_T = 1 nF, V_{PIN7} = V_{CC}, V_{PIN5} > V_{th}, V_{PIN2} = GND, all other pins open	Full range		4	mA

TYPICAL CHARACTERISTICS

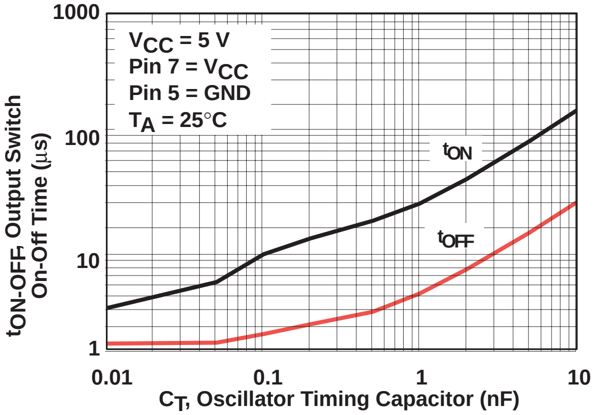


Figure 1. Output Switch On-Off Time vs Oscillator Timing Capacitor

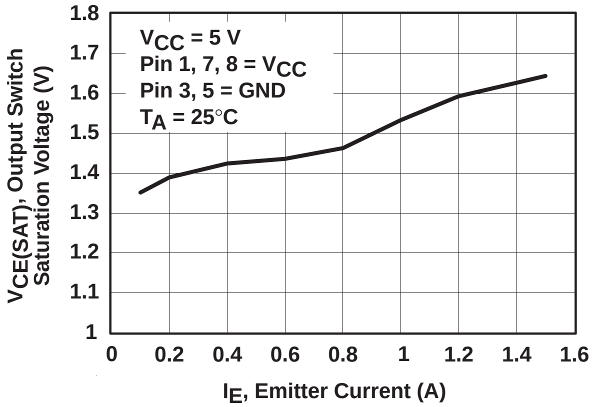


Figure 2. Output Switch Saturation Voltage vs Emitter Current (Emitter-Follower Configuration)

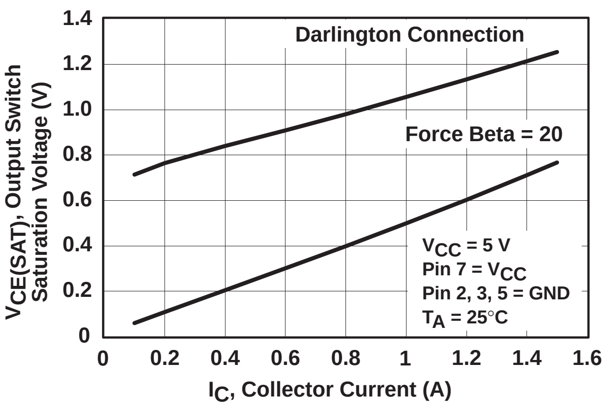


Figure 3. Output Switch Saturation Voltage vs Collector Current (Common-Emitter Configuration)

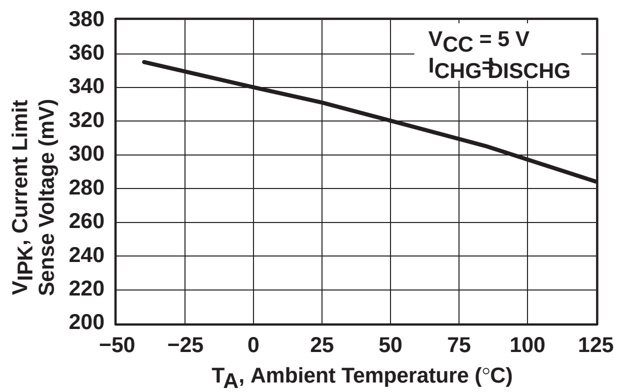


Figure 4. Current-Limit Sense Voltage vs Temperature

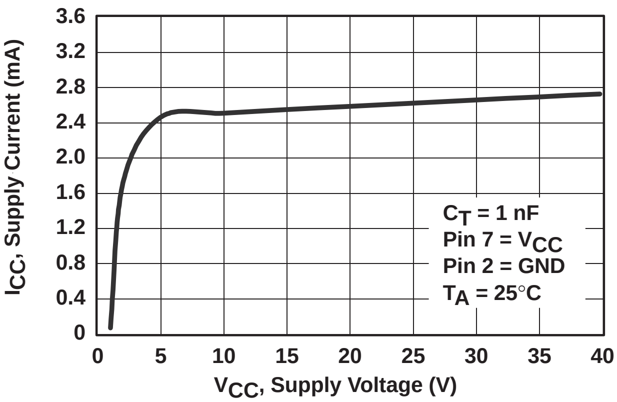
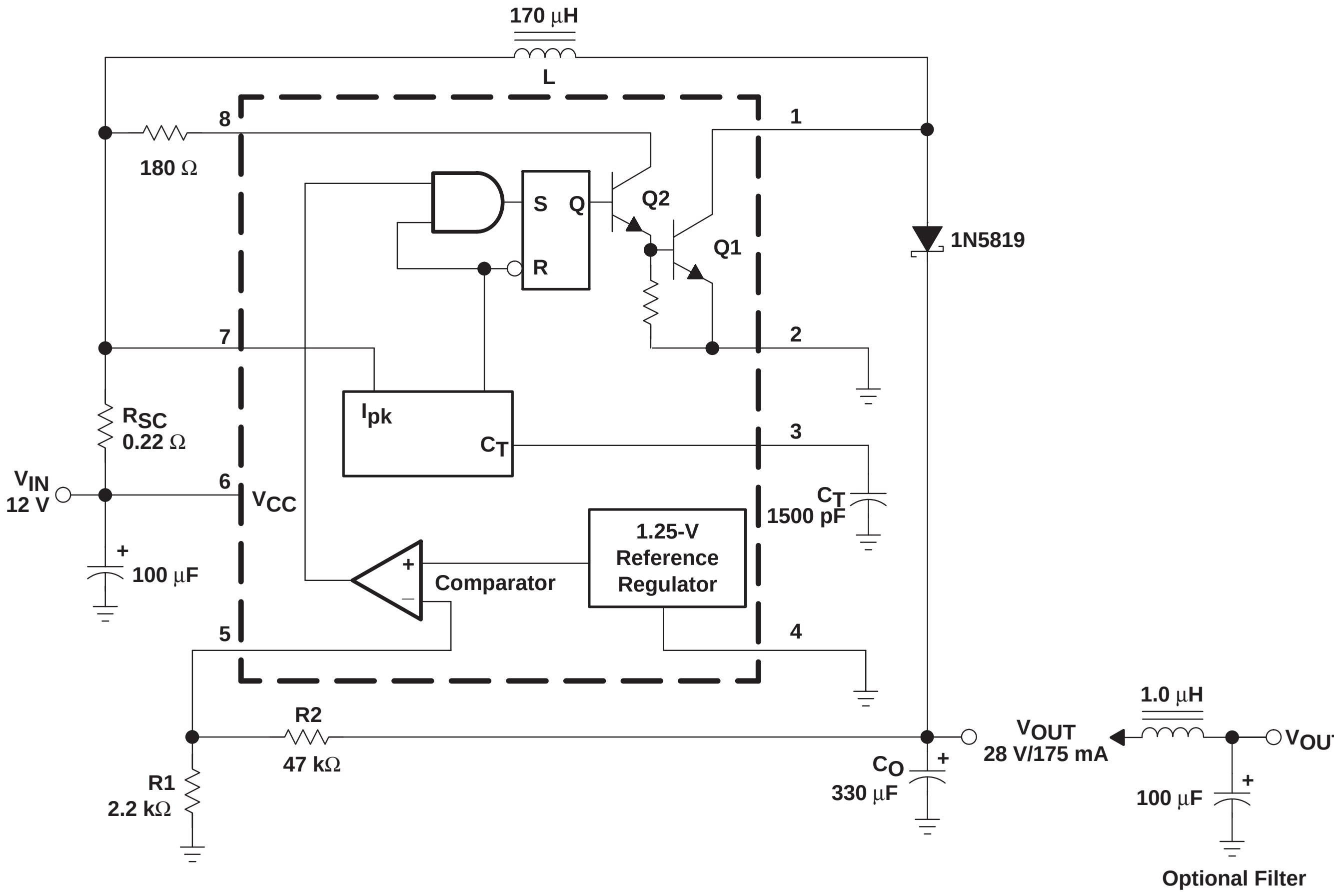


Figure 5. Standby Supply Current vs Supply Voltage

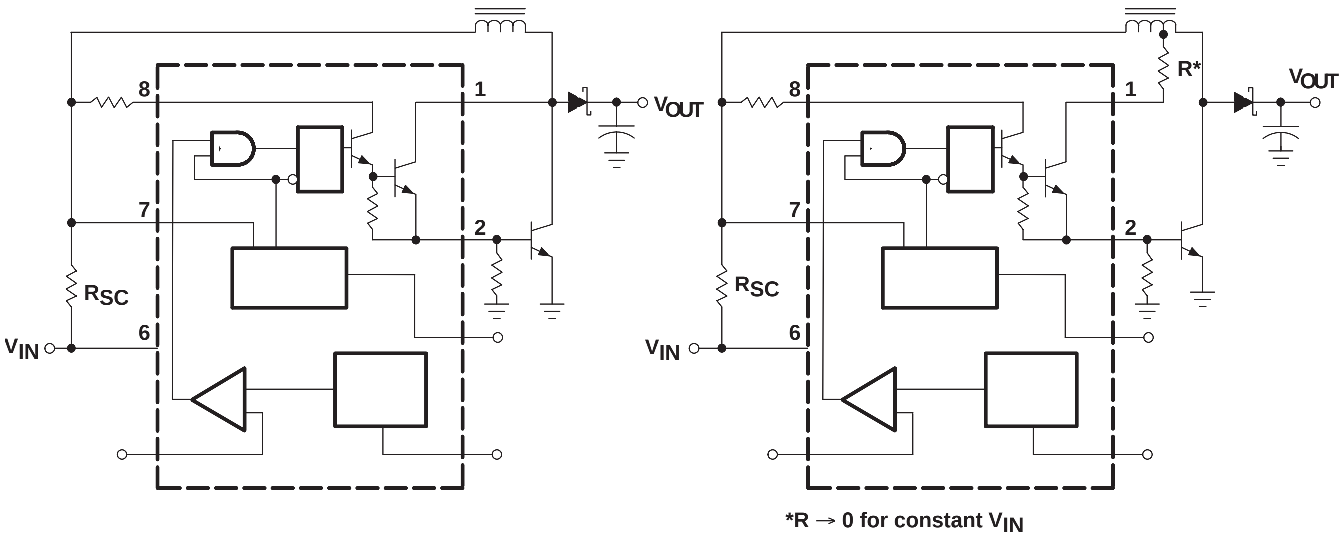
TYPICAL CHARACTERISTICS



TEST	CONDITIONS	RESULTS
Line Regulation	V_{IN} = 8 V to 16 V, I_O = 175 mA	30 mV ± 0.05%
Load Regulation	V_{IN} = 12 V, I_O = 75 mA to 175 mA	10 mV ± 0.017%
Output Ripple	V_{IN} = 12 V, I_O = 175 mA	400 mV_{PP}
Efficiency	V_{IN} = 12 V, I_O = 175 mA	87.7%
Output Ripple With Optional Filter	V_{IN} = 12 V, I_O = 175 mA	40 mV_{PP}

Figure 6. Step-Up Converter

TYPICAL CHARACTERISTICS

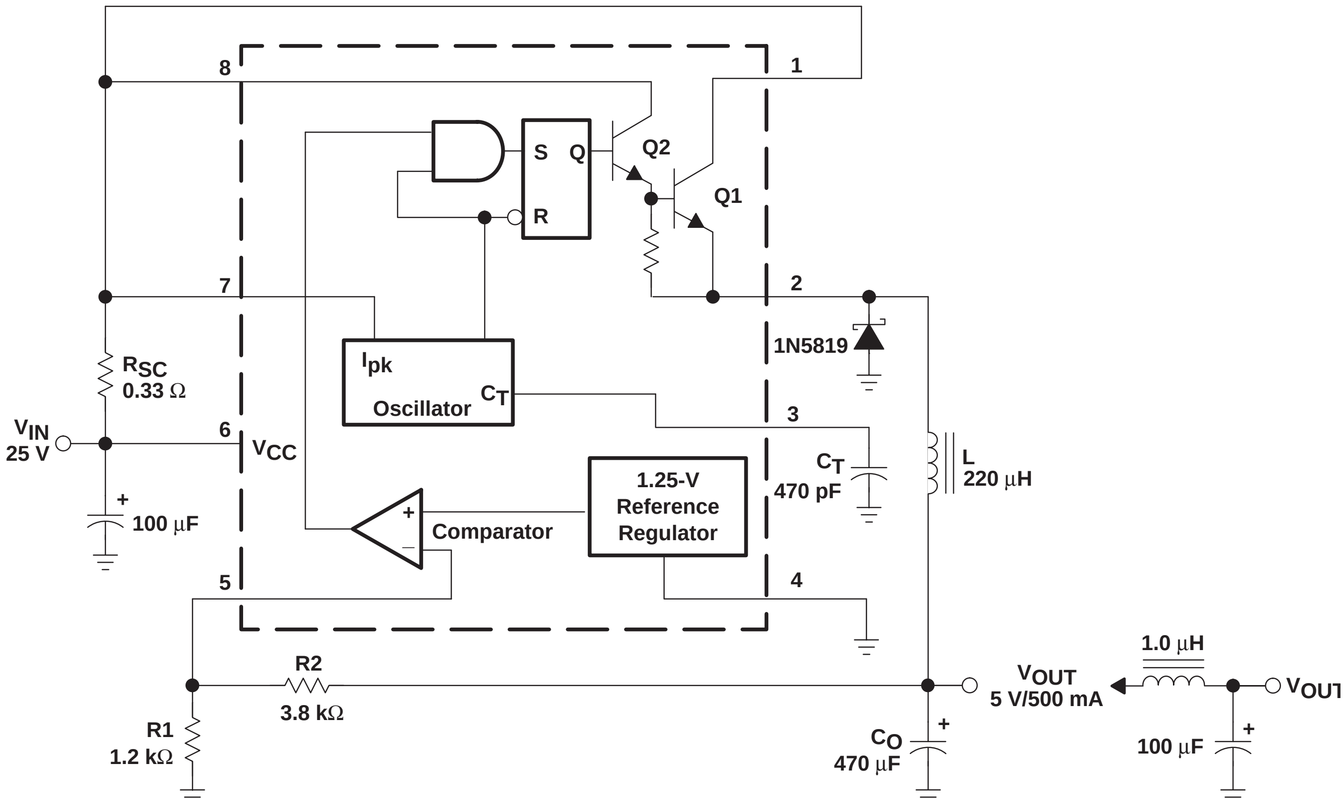


2a. External npn Switch **2b. External pnp Saturated Switch (see Note 5)**

NOTE 5: If the output switch is driven into hard saturation (non-Darlington configuration) at low switch currents (≤300 mA) and high driver currents (≥30 mA), it may take up to 2 µs to come out of saturation. This condition will shorten the off time at frequencies ≥30 kHz and is magnified at high temperatures. This condition does not occur with a Darlington configuration because the output switch cannot saturate. If a non-Darlington configuration is used, the output drive configuration in Figure 2b is recommended.

Figure 7. External Current-Boost Connections for I_C Peak Greater Than 1.5 A

TYPICAL CHARACTERISTICS



TEST	CONDITIONS	RESULTS
Line Regulation	V_{IN} = 15 V to 25 V, I_O = 500 mA	12 mV ± 0.12%
Load Regulation	V_{IN} = 25 V, I_O = 50 mA to 500 mA	3 mV ± 0.03%
Output Ripple	V_{IN} = 25 V, I_O = 500 mA	120 mV_{PP}
Short-Circuit Current	V_{IN} = 25 V, R_L = 0.1 Ω	1.1 A
Efficiency	V_{IN} = 25 V, I_O = 500 mA	83.7%
Output Ripple With Optional Filter	V_{IN} = 25 V, I_O = 500 mA	40 mV_{PP}

Figure 8. Step-Down Converter

TYPICAL CHARACTERISTICS

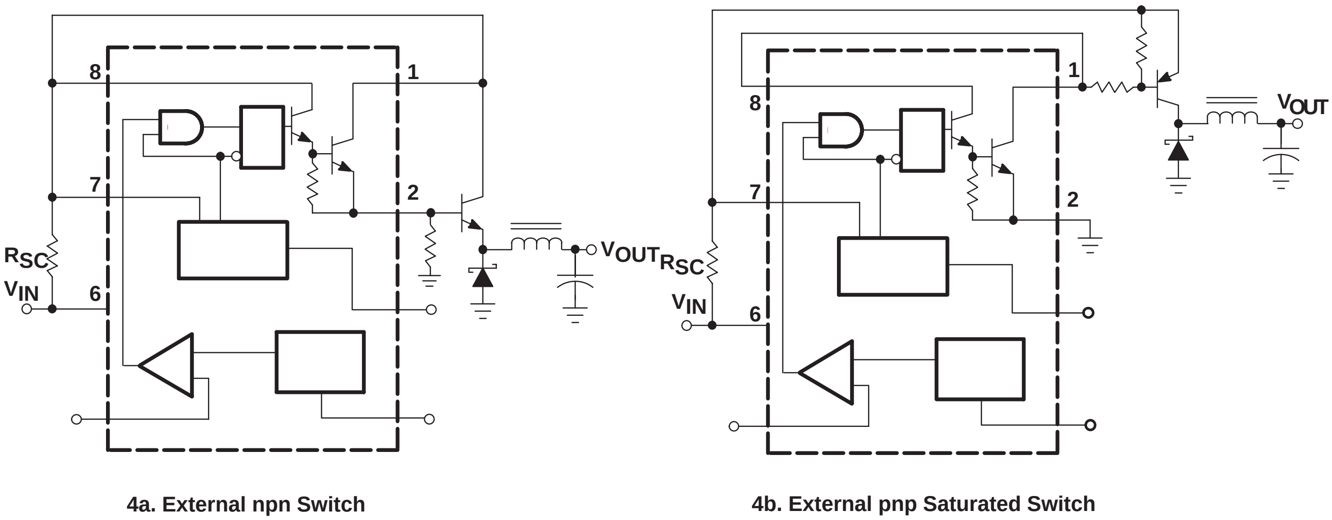
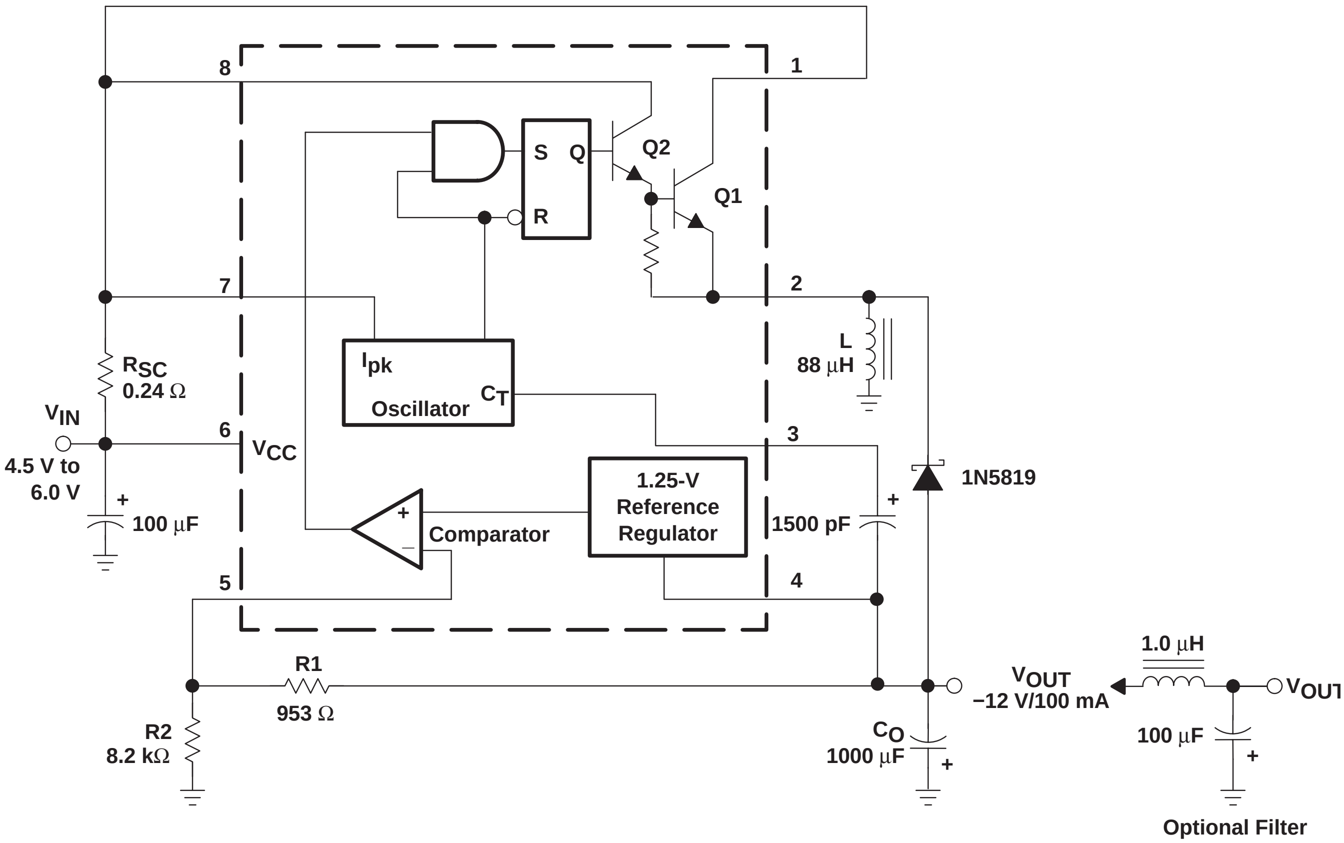


Figure 9. External Current-Boost Connections for I_C Peak Greater Than 1.5 A

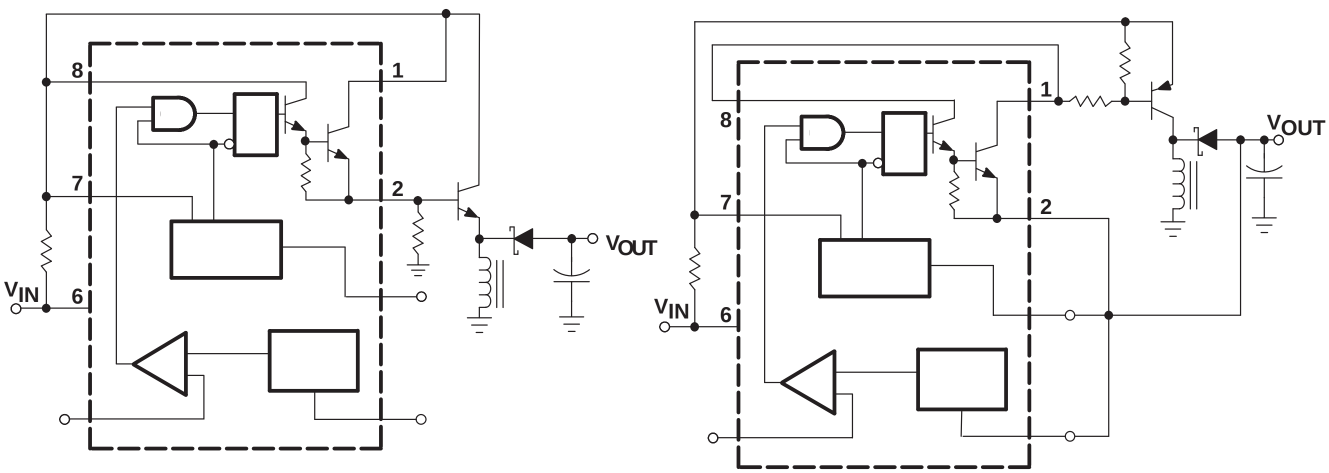
TYPICAL CHARACTERISTICS



TEST	CONDITIONS	RESULTS
Line Regulation	V_{IN} = 4.5 V to 6 V, I_O = 100 mA	3 mV ± 0.12%
Load Regulation	V_{IN} = 5 V, I_O = 10 mA to 100 mA	0.022 V ± 0.09%
Output Ripple	V_{IN} = 5 V, I_O = 100 mA	500 mV_{PP}
Short-Circuit Current	V_{IN} = 5 V, R_L = 0.1 Ω	910 mA
Efficiency	V_{IN} = 5 V, I_O = 100 mA	62.2%
Output Ripple With Optional Filter	V_{IN} = 5 V, I_O = 100 mA	70 mV_{PP}

Figure 10. Voltage-Inverting Converter

TYPICAL CHARACTERISTICS



6a. External npn Switch

6b. External pnp Saturated Switch

Figure 11. External Current-Boost Connections for I_C Peak Greater Than 1.5 A

APPLICATION INFORMATION

calculations of key parameters

CALCULATION	STEP UP	STEP DOWN	VOLTAGE INVERTING
t_{on}/t_{off}	$\frac{V_{out} + V_F - V_{in(min)}}{V_{in(min)} - V_{sat}}$	$\frac{V_{out} + V_F}{V_{in(min)} - V_{sat} - V_{out}}$	$\frac{\lvert V_{out}\rvert + V_F}{V_{in} - V_{sat}}$
$(t_{on} + t_{off})$	$\frac{1}{f}$	$\frac{1}{f}$	$\frac{1}{f}$
t_{off}	$\frac{t_{on} + t_{off}}{\frac{t_{on}}{t_{off}} + 1}$	$\frac{t_{on} + t_{off}}{\frac{t_{on}}{t_{off}} + 1}$	$\frac{t_{on} + t_{off}}{\frac{t_{on}}{t_{off}} + 1}$
t_{on}	$(t_{on} + t_{off}) - t_{off}$	$(t_{on} + t_{off}) - t_{off}$	$(t_{on} + t_{off}) - t_{off}$
C_T	$4 \times 10^{-5}\, t_{on}$	$4 \times 10^{-5}\, t_{on}$	$4 \times 10^{-5}\, t_{on}$
$I_{pk(switch)}$	$2I_{out(max)}\left(\frac{t_{on}}{t_{off}} + 1\right)$	$2I_{out(max)}$	$2I_{out(max)}\left(\frac{t_{on}}{t_{off}} + 1\right)$
R_{SC}	$\frac{0.3}{I_{pk(switch)}}$	$\frac{0.3}{I_{pk(switch)}}$	$\frac{0.3}{I_{pk(switch)}}$
$L_{(min)}$	$\left(\frac{(V_{in(min)} - V_{sat})}{I_{pk(switch)}}\right) t_{on(max)}$	$\left(\frac{(V_{in(min)} - V_{sat} - V_{out})}{I_{pk(switch)}}\right) t_{on(max)}$	$\left(\frac{(V_{in(min)} - V_{sat})}{I_{pk(switch)}}\right) t_{on(max)}$
C_O	$9\,\frac{I_{out} t_{on}}{V_{ripple(pp)}}$	$\frac{I_{pk(switch)}(t_{on} + t_{off})}{8V_{ripple(pp)}}$	$9\,\frac{I_{out} t_{on}}{V_{ripple(pp)}}$

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
MC33063AQDRQ1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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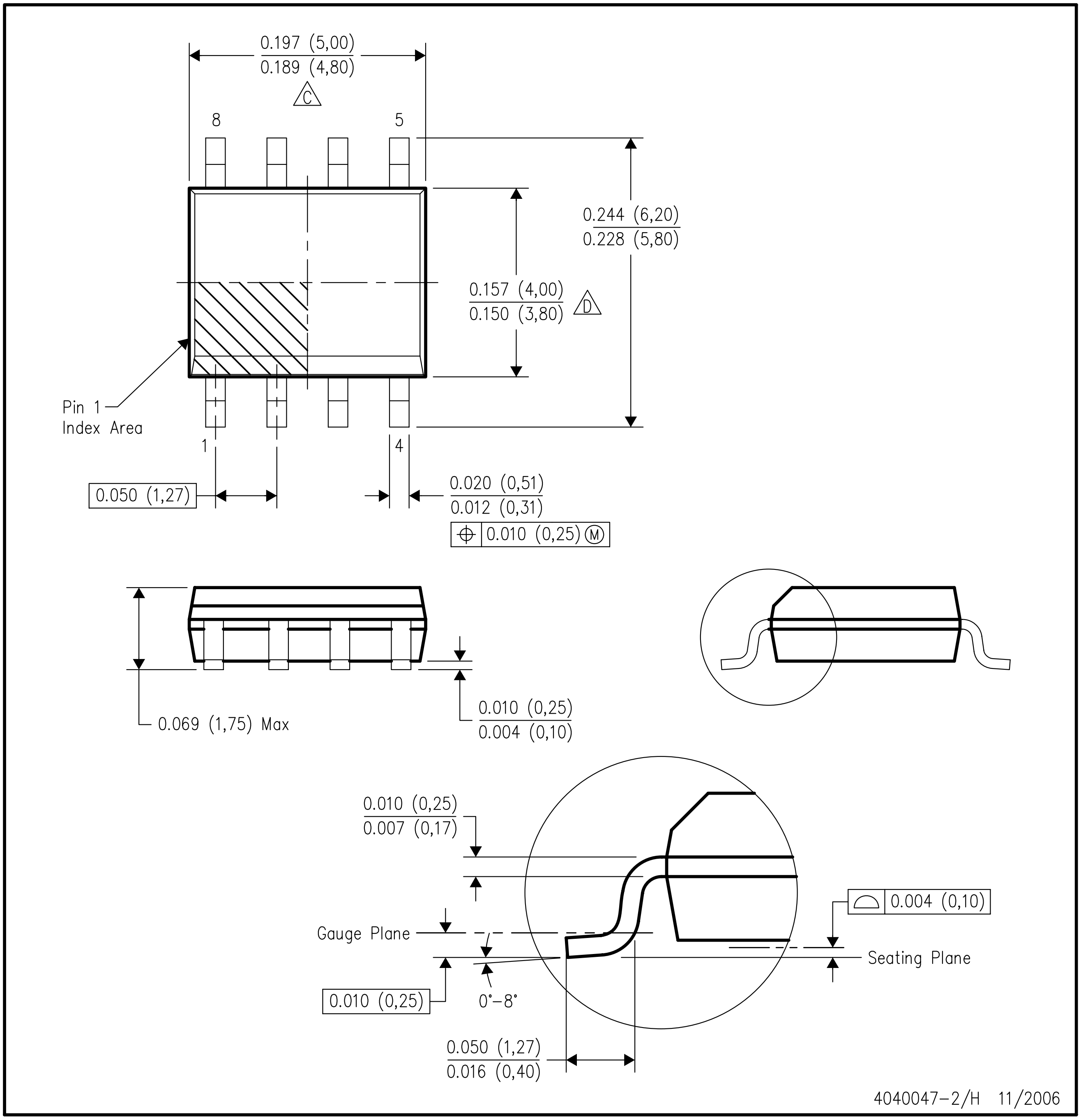
D (R-PDSO-G8) PLASTIC SMALL-OUTLINE PACKAGE



NOTES:
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.